SIEMENS

Data sheet

6DL1193-6BP00-0BX1



SIMATIC ET 200SP HA, ET 200SP, BaseUnit type X1, for Ex electronic modules, push-in terminals, WxH: 20 mm x 117 mm

General information	
Product type designation	BU type X1
Product function	
• I&M data	Yes; Asset data
Current carrying capacity	
For P1 and P2 bus, max.	10 A
For process terminals, max.	0.5 A
Hardware configuration	
Temperature sensor	Yes; For internal reference junction with connecting thermocouple
Formation of potential groups	
 support of potential groups 	Yes
 New potential group 	No
 Potential group continued from the left 	Yes
Slots	
 Number of slots 	1
Potential separation	
between backplane bus and supply voltage	Yes
between process terminals and supply voltage	Yes
Isolation	
Isolation tested with	further information on insulation can be found in the "ET 200SP HA / ET 200SP modules for devices in hazardous areas" System Manual
Ambient conditions	
Ambient temperature during operation	
 horizontal installation, min. 	-40 °C
 horizontal installation, max. 	70 °C
 vertical installation, min. 	-40 °C
 vertical installation, max. 	60 °C
Altitude during operation relating to sea level	
 Installation altitude above sea level, max. 	2 000 m
connection method / header	
Terminals	
Terminal type	Push-in terminal
 Conductor cross-section, min. 	0.14 mm²; AWG 26
 Conductor cross-section, max. 	2.5 mm²; AWG 14
 Number of process terminals to I/O module 	8
Dimensions	
Width	20 mm
Height	117 mm
Depth	35 mm
Weights	

Weight, approx.

last modified:

42 g

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